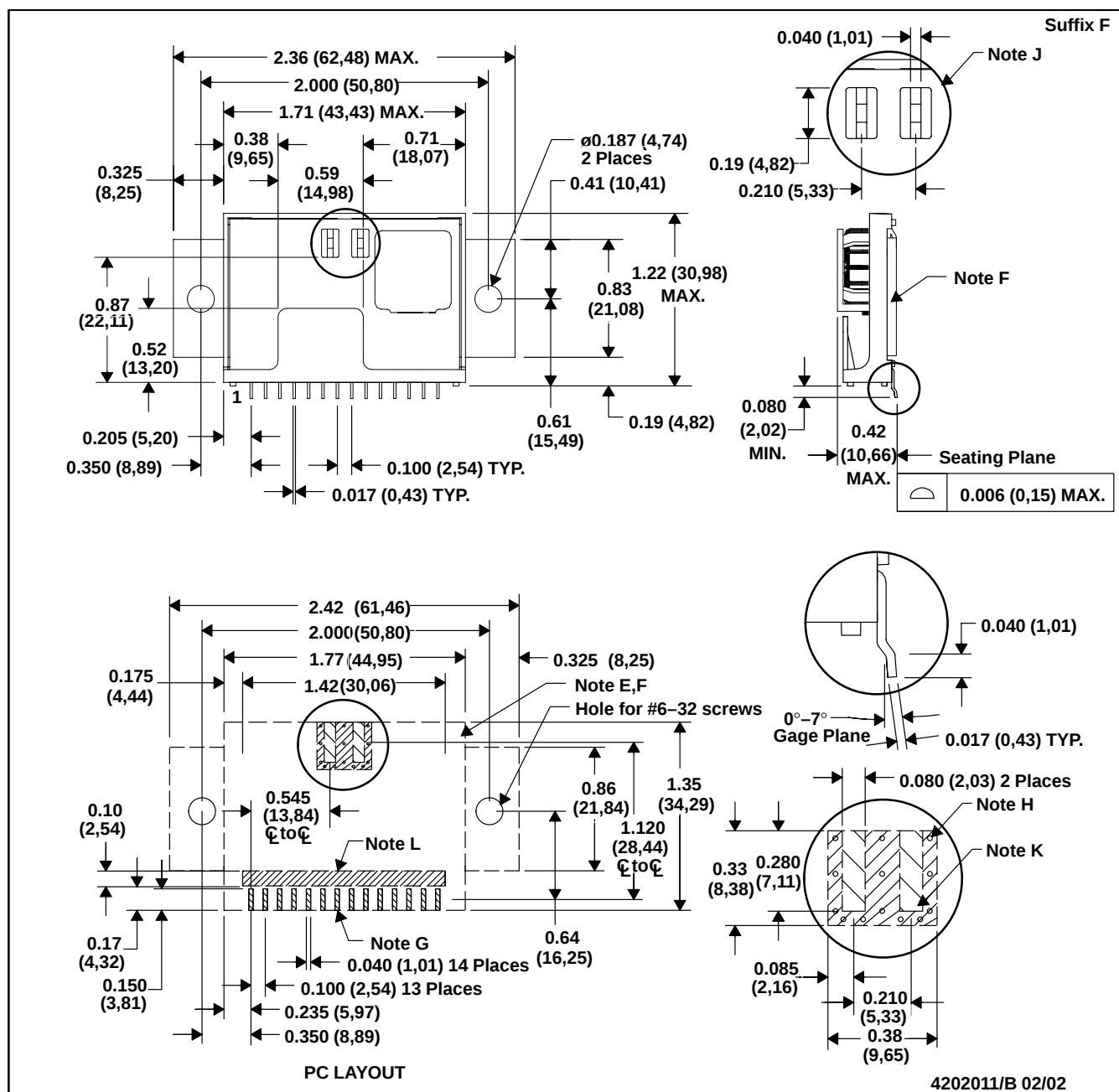


EEF (R-PSIP-G14)

PLASTIC SINGLE-IN-LINE MODULE



- NOTES: A. All linear dimensions are in inches (mm).
 B. This drawing is subject to change without notice.
 C. 2-place decimals are ± 0.030 (± 0.76 mm).
 D. 3-place decimal are ± 0.010 (± 0.25 mm).
 E. Recommended mechanical keep-out area.
 F. The metal tab is isolated but electrically conductive.
 No signal traces are allowed under the metal tab area.
 A solid copper island is recommended, which may be grounded.
 G. Power pin connections should utilize two or more vias per input, ground and output pin.

- H. Minimum copper land area required for solder tab.
 Vias are recommended to improve copper adhesion or connect land to other ground area.
 J. Underside solder tabs detail.
 K. Solder mask openings to copper island for solder joints to mechanical pins.
 L. No copper, power or signal traces in this area.

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